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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of	:	
DiStefano, et al.	:	Group Art Unit: 2812
	:	
U.S. Application No. 09/638,079	:	
	:	Examiner:
	:	
Filed: August 14, 2000	:	
	:	
For: METHODS FOR PROVIDING	:	Date: November 28, 2000
VOID-FREE LAYERS FOR	:	
SEMICONDUCTOR ASSEMBLIES	:	
	:	
	X	

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Preliminary to initiation of the prosecution of the above-identified U.S. patent application, the following amendments and remarks are respectfully submitted.

IN THE ABSTRACT

Please delete the Abstract originally filed with this application, and substitute therefor the enclosed revised Abstract.

IN THE CLAIMS

Please cancel claim 1 and substitute therefor the following new claims:

al
contd

1/. A method of providing a substantially void free underfill for a flip chip assembly, comprising:

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on November 28, 2000.

(Signature)
Kimberly V. Perry

Typed or Printed Name of Person Signing Certificate

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02 FC:102 400.00 CH

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